

PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APG-ABD/14/8764 Dated 13 Nov 2014

VIPower M05 in PSSO-12 (Deep Down Set): Activation of Shenzhen as additional Assembly / Testing Location

Table 1. Change Implementation Schedule

Forecasted implementation date for change	27-Apr-2015
Forecasted availability date of samples for customer	31-Jan-2015
Forecasted date for STMicroelectronics change Qualification Plan results availability	20-Feb-2015
Estimated date of changed product first shipment	30-Apr-2015

Table 2. Change Identification

Product Identification (Product Family/Commercial Product)	see list	
Type of change	Package assembly material change, Assembly additional location, Testing additional location	
Reason for change	Service	
Description of the change	Please be informed that we are going to activate ST Shenzhen (China) as additional assembly and testing location, beside ST Bouskoura (Morocco), for VIPower M05 devices housed in PowerSSO-12 package Deep Down Set version. We will introduce "strip test" in Final Test as well. Strip test consists in testing the device directly on the Lead Frame form (strip) before singulating it (2nd crop). Same test coverage and quality will be applied.Bill of material will change as per enclosed change matrix:	
Change Product Identification	Dedicated Finished-Good codes	
Manufacturing Location(s)	1]St Bouskoura 2 - Morocco	

Table 3. List of Attachments

Customer Part numbers list	
Qualification Plan results	

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Customer Acknowledgement of Receipt	PCN APG-ABD/14/8764
Please sign and return to STMicroelectronics Sales Office	Dated 13 Nov 2014
Qualification Plan Denied	Name:
Qualification Plan Approved	Title:
	Company:
🗖 Change Denied	Date:
Change Approved	Signature:
Remark	

Name	Function	
Liporace, Nicola	Marketing Manager	
Nicoloso, Riccardo	Product Manager	
Minerva, Francesco	Q.A. Manager	

DOCUMENT APPROVAL



VIPower M05 in PSSO-12 (Deep Down Set): Activation of Shenzhen as additional Assembly and Testing Location

WHAT:

Please be informed that we are going to activate ST Shenzhen (China) as additional assembly and testing location, beside ST Bouskoura (Morocco), for VIPower M05 devices housed in PowerSSO-12 package Deep Down Set version. We will introduce "strip test" in Final Test as well.

Strip test consists in testing the device directly on the Lead Frame form (strip) before singulating it (2nd crop). Same test coverage and quality will be applied.

Bill of material will change as per below change matrix:

	Bouskoura	Shenzhen
Mold Compound	SUMITOMO EME7026	SUMITOMO EME G700LS
Wires	Cu 2,5 mils/Au 1.3 mils	Cu 2,5 mils/Cu 1.2 mils
Die Attach	Preform Pb/Ag/Sn	Preform Pb/Ag/Sn
Lead frame	Matrix 3x8	High Density (256 units)

WHY:

Service

HOW:

Qualification report according to AEC-Q100 will be available on February 2015 (wk08/2015)

WHEN:

From April 2015, but we are ready ship parts prior this date upon Customer agreement. Sample will be available on demand from end of February 2015.

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PCN Title : VIPower M05 in PSSO-12 (Deep Down Set): Activation of Shenzhen as additional Assembly / Testing Location PCN Reference : APG-ABD/14/8764 PCN Created on : 30-NOV-2014

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change:

ST COMMERCIAL PRODUCT

VN5050AJ-E	VN5050AJTR-E	VN5050J-E
VN5050JTR-E	VN5E050AJ-E	VN5E050AJTR-E
VN5E050J-E	VN5E050JTR-E	VN5E050MJ-E
VN5E050MJTR-E	VND5160AJ-E	VND5160AJTR-E
VND5E160AJ-E	VND5E160AJTR-E	VND5E160J-E
VND5E160JTR-E	VND5E160MJ-E	VND5E160MJTR-E

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